

# Using the UCC28070EVM

## User's Guide



Literature Number: SLUU312B  
May 2008–Revised May 2009

# ***UCC28070 300-W Interleaved PFC Pre-Regulator User's Guide***

---

---

---

## **1 Introduction**

The UCC28070 evaluation module is a 300-W, two phase interleaved, PFC pre-regulator that uses average current mode control techniques to achieve near unity power factor. The pre-regulator was designed to operate off a universal ac line input of 85 V to 265 V and provides a regulated 390-V dc output. This evaluation module demonstrates TI's interleaved PFC control technology.

## **2 Description**

The pre-regulator uses the UCC28070 PFC interleaved controller to shape the input current wave form to provide power factor correction.

## **3 Thermal Requirements**

- The evaluation module works up to 300 W without external cooling in ambient temperature of 25°C.

## **4 Electrical Specifications**

**Table 1. Specification Table**

| DEFINITION                         | MINIMUM | TYPICAL | MAXIMUM | UNITS |
|------------------------------------|---------|---------|---------|-------|
| RMS Input Voltage (ac line)        | 85      |         | 265     | V     |
| Output Voltage (V <sub>OUT</sub> ) |         | 390     |         |       |
| Line Frequency                     | 47      |         | 63      | Hz    |
| Power Factor (PF) at Maximum Load  | 0.9     |         |         |       |
| Output Power                       |         |         | 300     | W     |
| Full Load Efficiency               | 90      |         |         | %     |

## 5 Schematics

To evaluate inductor ripple currents jumpers JP1 and JP2 can be removed and replaced with current loops.

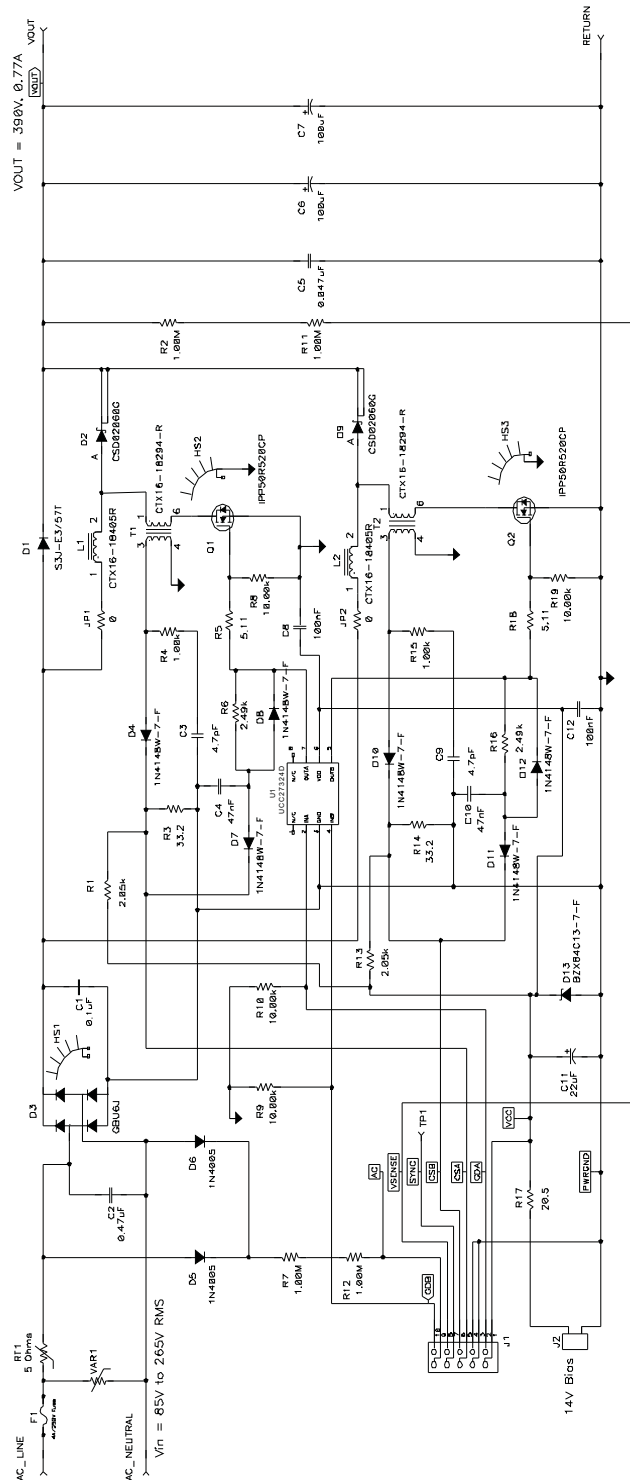


Figure 1. Interleaved PFC Power Stage (Mother Board HPA225)

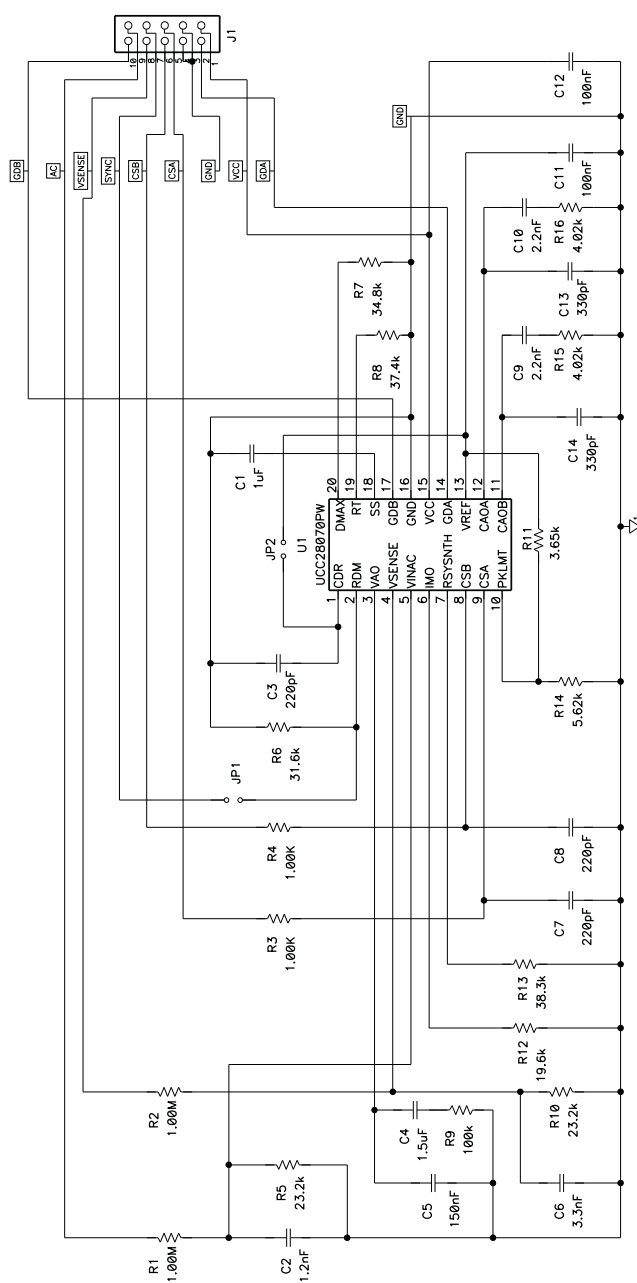


Figure 2. Controller Circuitry (Daughter Board HPA284)

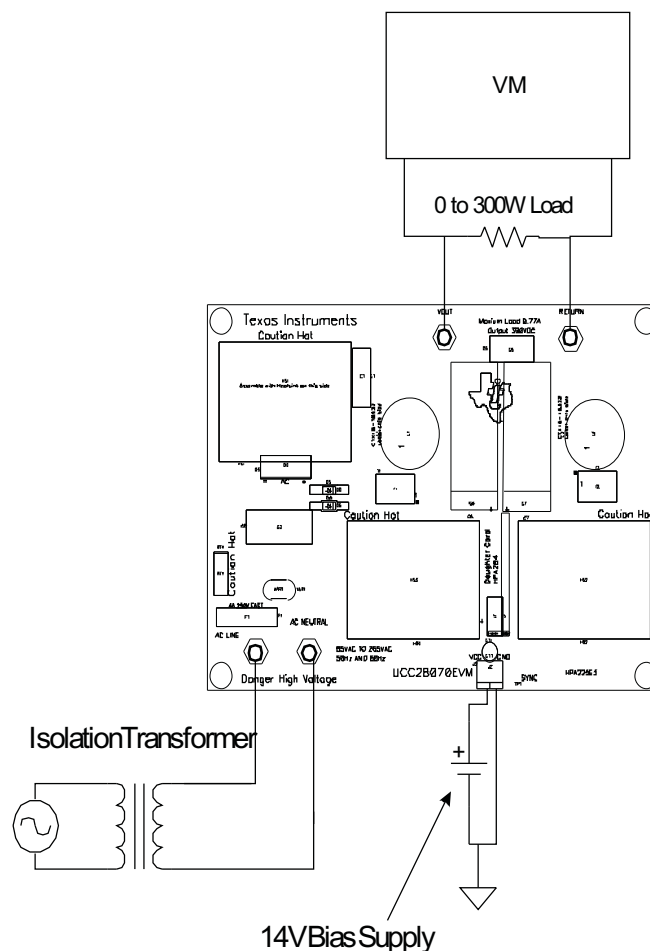
## 6 Warning

There are high voltages present on the pre-regulator and it should only be handled by experienced power supply professionals. To evaluate this board as safely as possible the following test set up should be used. An isolation transformer should be connected between the source and unit. Before power is supplied a voltmeter and a resistive or electronic load should be attached to the unit's output.

## 7 Test Setup and Power Up/Power Down Instructions

A separate 14-V bias supply is required to power the UCC28070 control circuitry. The unit will start up under no load conditions. However, for safety, a load should be connected to the output of the device before it is powered up. It is advised that resistive loads be used. Constant current or constant power loads could damage the evaluation board. The unit should also never be handled when power is applied to it or the output voltage is above 50-V dc. Please refer to [Figure 3](#) for the test setup diagram.

**Note:** There are very high voltages on the board and components can and will reach temperatures above 100 °C, so caution must be taken in handling the board.



**Figure 3. Test Setup**

## 8 Performance Data

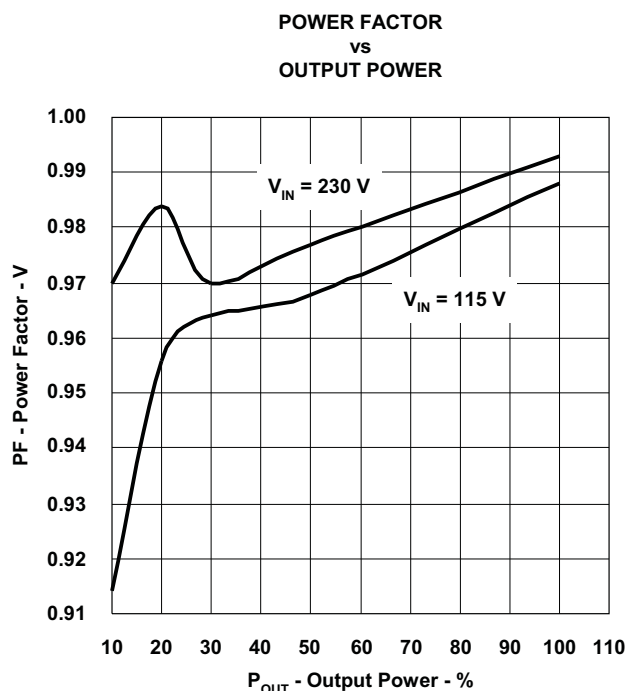


Figure 4. Power Factor at  $V_{IN} = 115\text{ V}$  and  $230\text{ V RMS}$

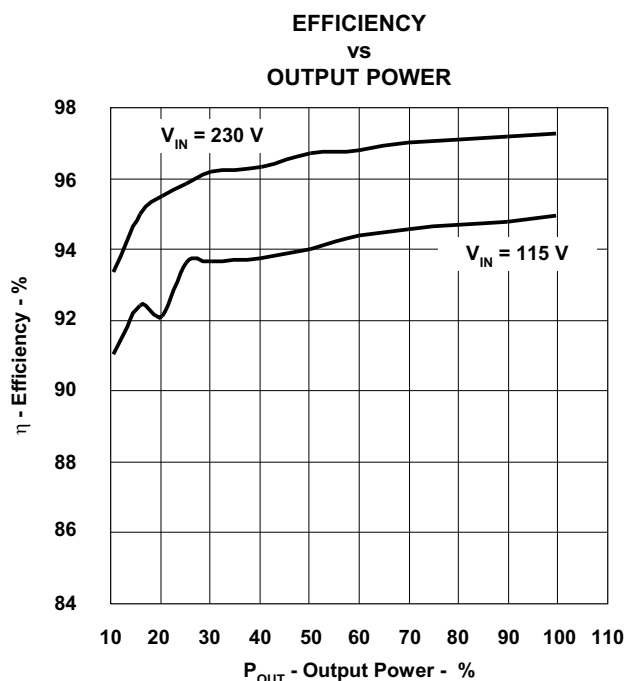


Figure 5. Efficiency at  $V_{IN} = 115\text{ V}$  and  $230\text{ V RMS}$

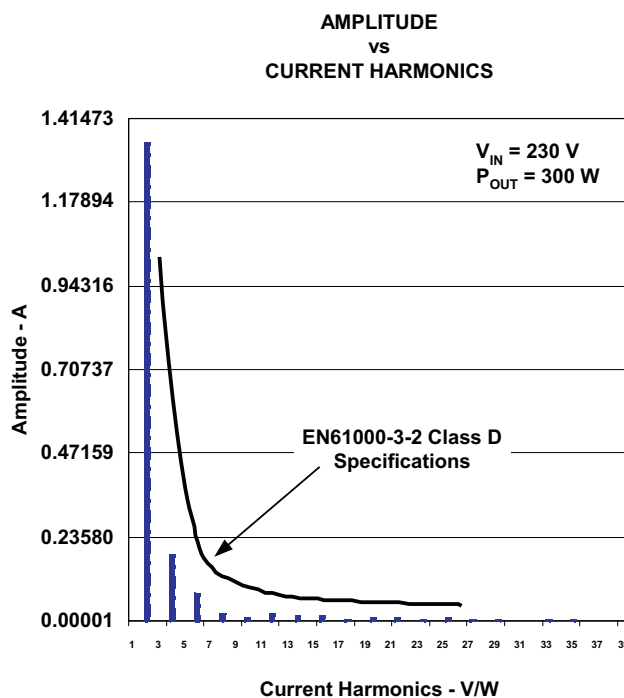
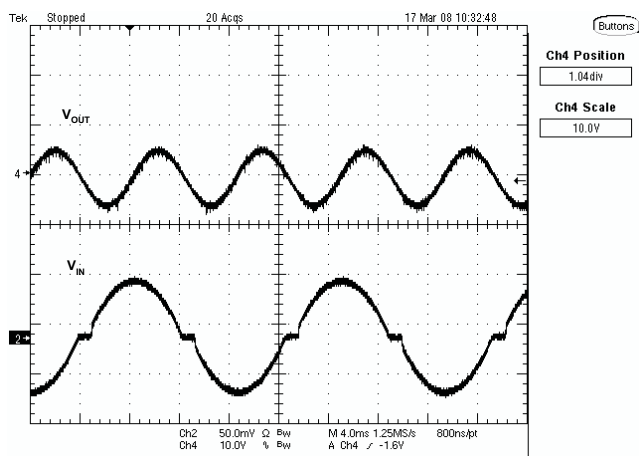
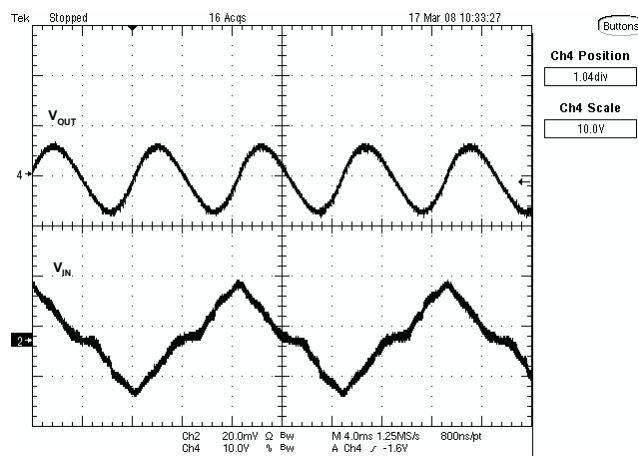


Figure 6. Input Current Harmonics at  $V_{IN} = 230\text{ V}$ ,  $P_{OUT} = 300\text{ W}$

## 8.1 Input Current and Output Ripple Voltage at Full Load



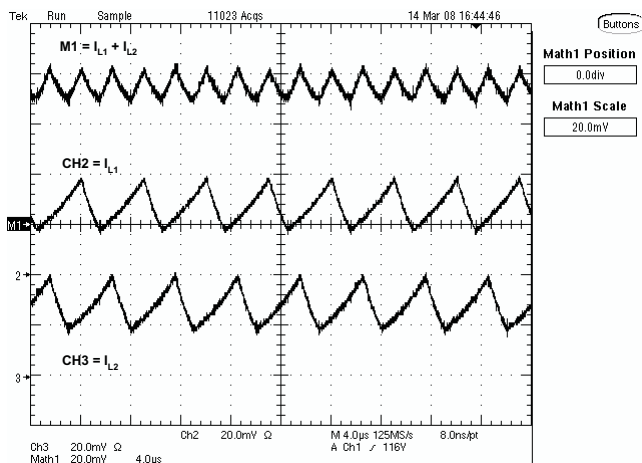
**Figure 7. Input Ripple Current ( $I_{IN}$ ), Output Ripple Voltage ( $V_{OUT}$ ),  $V_{IN}$  = 85 V RMS,  $P_{OUT}$  = 300 W**



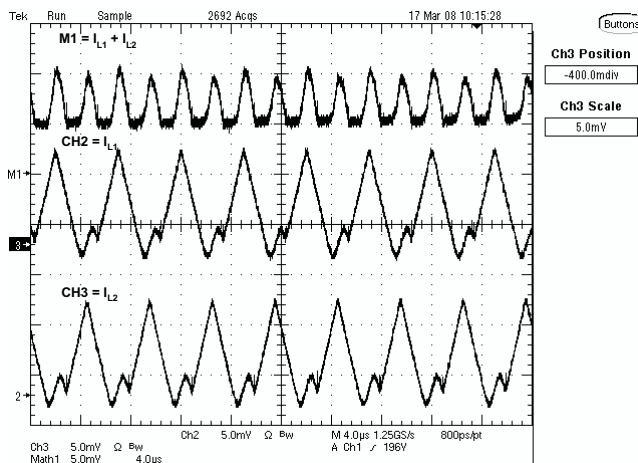
**Figure 8. Input Ripple Current ( $I_{IN}$ ), Output Ripple Voltage ( $V_{OUT}$ ),  $V_{IN}$  = 265 V RMS,  $P_{OUT}$  = 300 W**

## 8.2 Input Ripple Current Cancellation

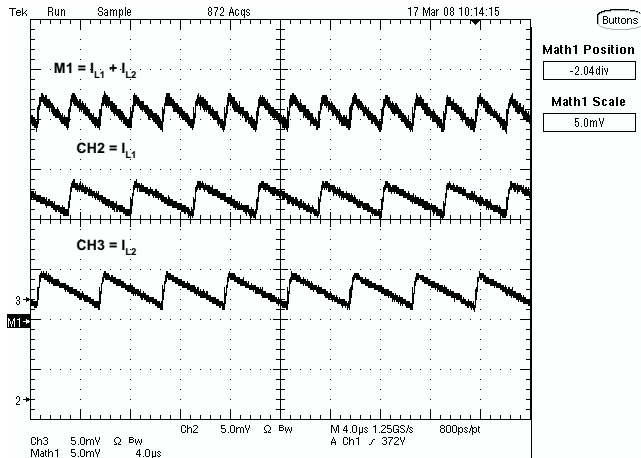
The following waveforms show input current ( $M1 = I_{L1} + I_{L2}$ ), Inductor Ripple Current ( $I_{L1}$ ,  $I_{L2}$ ) versus rectified line voltage. From these curves it can be observed that interleaving reduces the magnitude of input ripple current caused by the inductor ripple current.



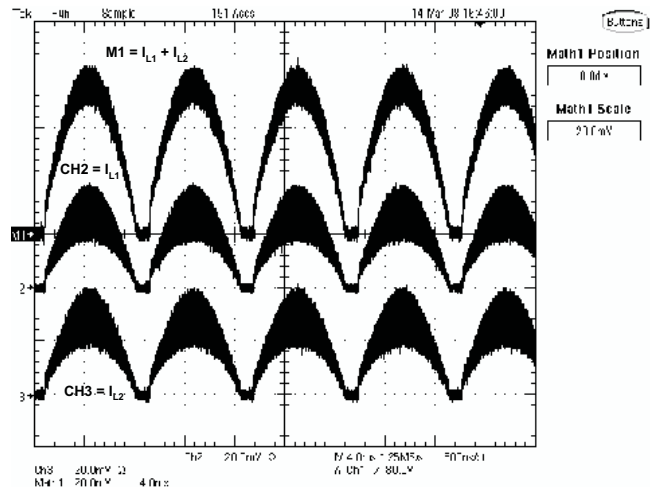
**Figure 9. Inductor and Input Ripple Current at  $V_{IN}$  = 85 V RMS at the Peak of Line**



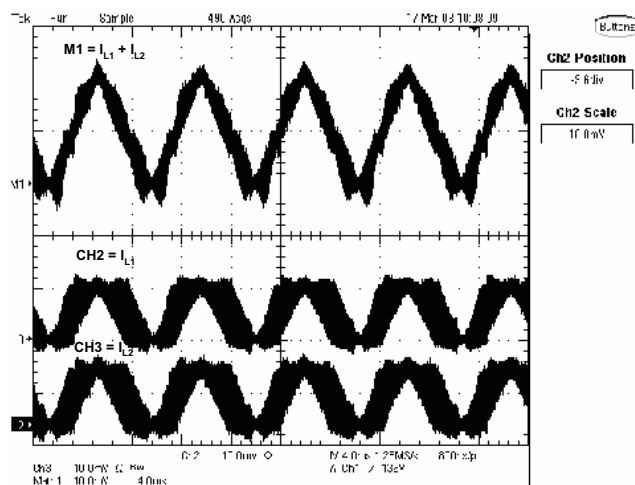
**Figure 10. Inductor and Input Ripple Current at 265 V RMS Input at the Half Output Voltage**



**Figure 11. Inductor and Input Ripple Current at 265 V RMS Input at Peak of the Line Voltage**



**Figure 12. Input and Inductor Ripple Current at  $V_{IN} = 85$  V RMS,  $P_{OUT} = 300$  W**



**Figure 13. Input and Inductor Ripple Current at  $V_{IN} = 265$  V RMS,  $P_{OUT} = 300$  W**



### 8.3 Startup Characteristics

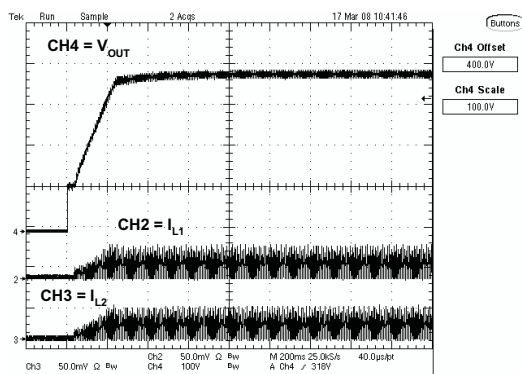


Figure 14. Start Up at  $V_{IN} = 85\text{ V}$ ,  
 $P_{OUT} = 300\text{ W}$

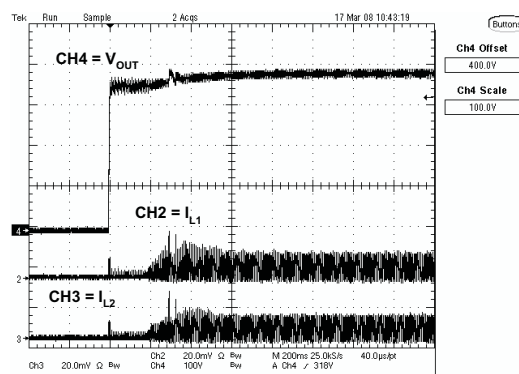


Figure 15. Start Up at  $V_{IN} = 265\text{ V}$ ,  
 $P_{OUT} = 300\text{ W}$

### 8.4 Line Dropout

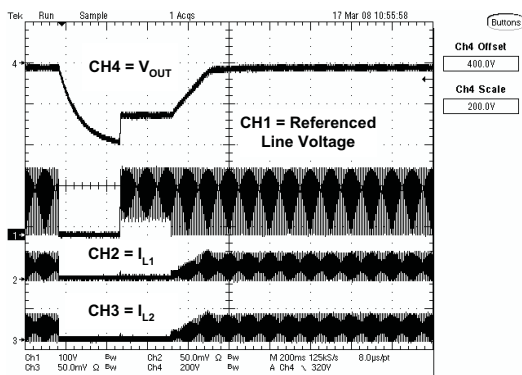


Figure 16. Line Dropout at 115 V RMS

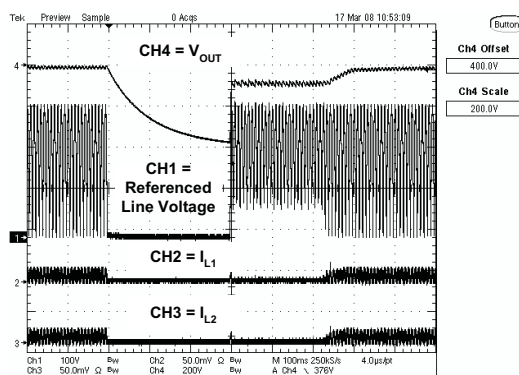


Figure 17. Line Dropout at 230 V RMS

## 8.5 Frequency Dithering

Frequency dithering has shown to reduce EMI. The UCC28070 EVM was design to operate in frequency dithering mode and none frequency dithering mode. When the JP1 and JP2 jumpers on the daughter board are shorted the PWM is operating in a fix frequency mode. The fixed frequency was set to 200 kHz per phase. When Jumpers JP1 and JP2 are open the converter is running in frequency dither mode. The single phases switching frequency was set to vary from roughly 190 kHz per phase to 210 kHz per phase.

When frequency dithering was applied to the EVM a 4.35 dBuV reduction in the Quasi Peak (QP) EMI measurement was observed.

**Note:** A filter was added to the front end of the EVM to clean up some of the noise to take EMI data. Depending on the filter the amount of EMI will vary. Also, this filter was not setup to pass EMI requirements but to show frequency dithering can reduced EMI.

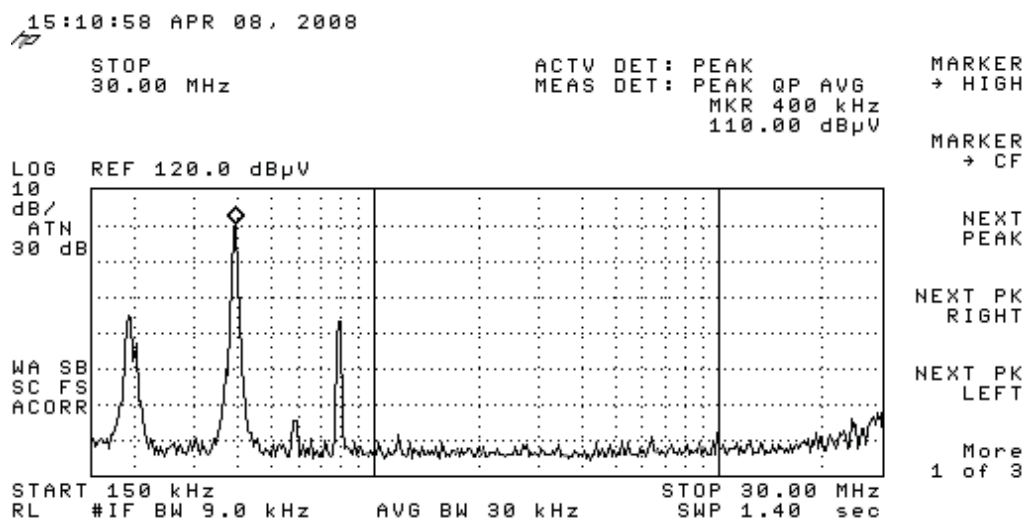


Figure 18. EMI Quasi Peak (QP) Measurement Without Frequency Dithering, No EMI Filter Present

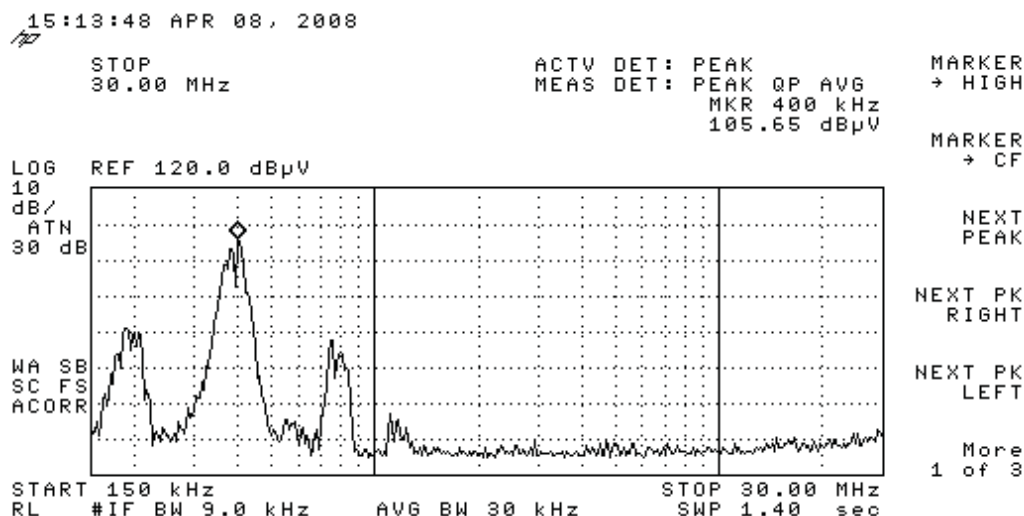
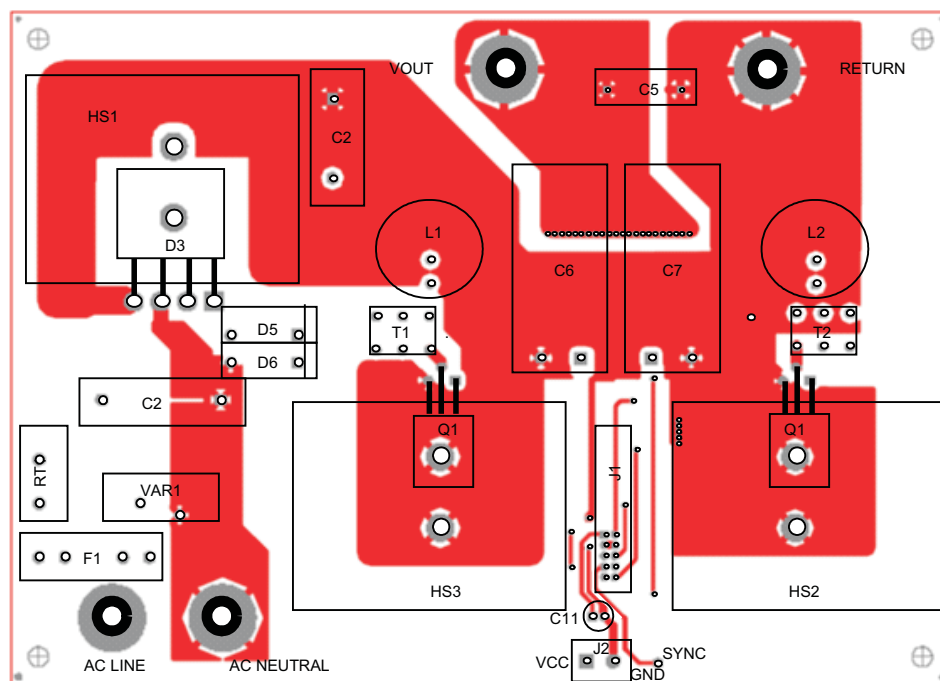
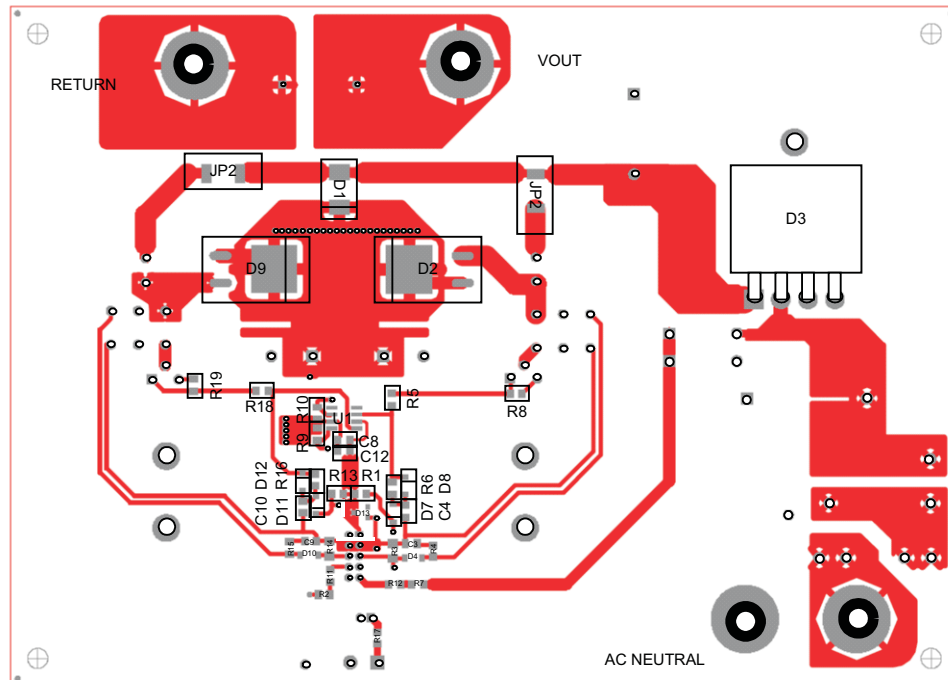


Figure 19. EMI Quasi Peak (QP) Measurement With Frequency Dithering, No EMI Filter Present

## 9 Reference Design Assembly Drawing



**Figure 20. Mother Board, Top Assembly and Copper Layer**



**Figure 21. Mother Board Bottom, Assembly and Copper Layer**

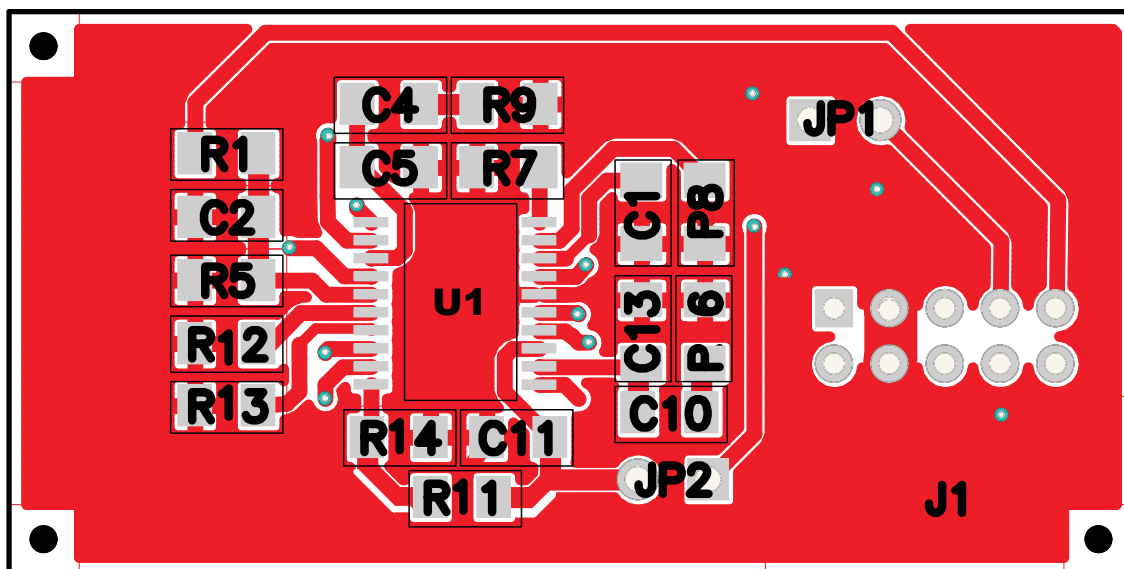


Figure 22. Daughter Board, Top Assembly and Copper Layer

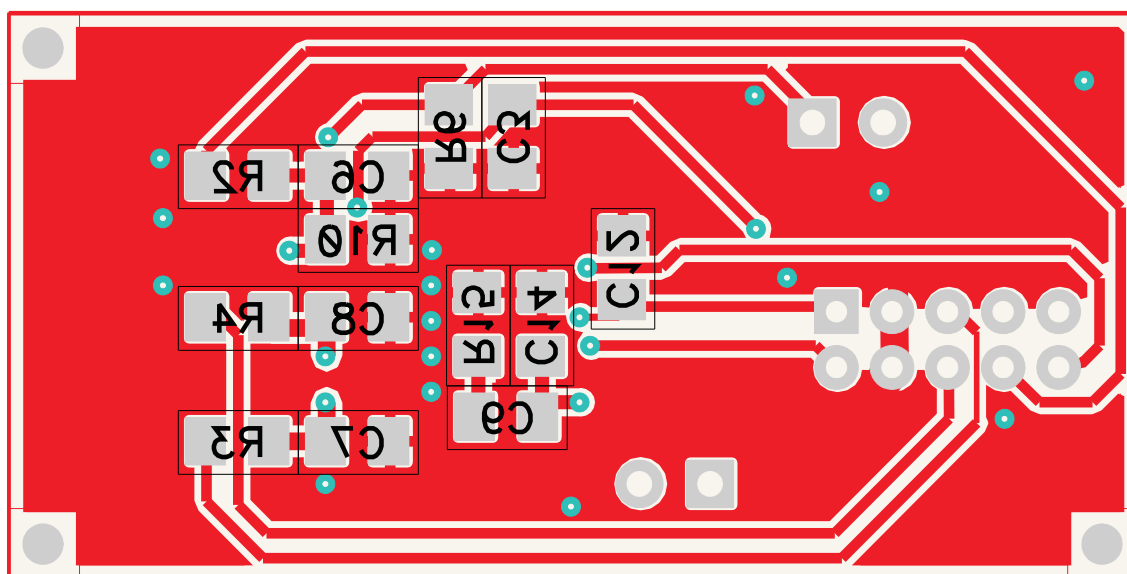


Figure 23. Daughter Board, Top Assembly and Copper Layer

## 10 List of Materials

### 10.1 Mother Board List of Materials

**Table 2. Mother Board**

| COUNT | REF DES                           | DESCRIPTION   | MFR              | PART NUMBER         |
|-------|-----------------------------------|---|------------------|---------------------|
| 4     | AC_LINE, AC_NEUTRAL, RETURN, VOUT | Connector, banana jack, uninsulated, 3267, 0.500 dia. inch          | Pomona           | 3267                |
| 1     | C1                                | Capacitor, film, 275 VAC, 20%, 0.1 $\mu$ F, 0.689 x 0.236 inch      | Panasonic        | ECQU2A104BC1        |
| 1     | C11                               | Capacitor, aluminum, 35 V, 20%, 22 $\mu$ F, 0.200 * 0.435 inch      | Panasonic        | ECA-1VM220          |
| 1     | C2                                | Capacitor, film, 275 VAC, 20%, 0.47 $\mu$ F, 0.236 X 0.591          | Panasonic        | ECQ-U2A474MG        |
| 2     | C3, C9                            | Capacitor, ceramic, 25 V, X7R, 10%, 4.7 pF, 805                     | Std              | Std                 |
| 2     | C4, C10                           | Capacitor, ceramic, 25 V, X7R, 10%, 47 nF, 805                      | Std              | Std                 |
| 1     | C5                                | Capacitor, polyester, 630 V, 10%, 0.047 $\mu$ F, 0.256 x 0.650 inch | Panasonic        | ECQ-E6473KZ         |
| 2     | C6, C7                            | Capacitor, aluminum, 450 VDC, 20%, 100 $\mu$ F, 18 x 40 mm          | Nippon Chemi-con | EKXG451ELL101MM4 0S |
| 2     | C8, C12                           | Capacitor, ceramic, 25 V, X7R, 10%, 100 nF, 805                     | Std              | Std                 |
| 1     | D1                                | Diode, 3000 mA, 600 V, SMC  | Vishay           | S3J-E3/57T          |
| 1     | D13                               | Diode, zener, 13 V, 300 mW, SOT-23                                  | Diodes           | BZX84C13-7-F        |
| 2     | D2, D9                            | Diode, Schottky Rectifier, 2 A, 600 V, TO-263-2                     | CREE             | CSD02060G           |
| 1     | D3                                | Diode, bridge, 6 A, 600 V, BU6                                      | Vishay           | GBU6J               |
| 6     | D4, D7, D8, D10, D11, D12         | Diode, signal, 200 mA, 100 V, 350 mW, SOD-123                       | Diodes           | 1N4148W-7-F         |
| 2     | D5, D6                            | Diode, signal, 600 V, 1 A, DO-41                                    | Diodes           | 1N4005              |
| 1     | F1                                | Fuse clip, 5x20 mm, 4 A/250 V fuse, 0.205 x 0.220 inch x2           | Wickmann         | 0100056H            |
| 3     | HS1, HS2, HS3                     | Heat sink, universal-mount TO-220, 1.500 x 2.000 inch               | Aavid Thermalloy | 600703U01500G       |
| 1     | J1                                | Receptacle, 10 pins, 0.200 x 0.472 inch                             | HRS              | DF11-10DS-2DSA(05)  |
| 1     | J1                                | Assembled daughter board controller, HPA284                         | Std              | Std                 |
| 1     | J2                                | Terminal block, 2 pin, 15 A, 5.1 mm, 0.40 x 0.35 inch               | OST              | ED1609              |
| 2     | JP1, JP2                          | Resistor, chip, 1 W, 5%, 0, 2512                                    | Std              | Std                 |
| 2     | L1, L2                            | Inductor, 140 $\mu$ H at 3.2 A pk, 0.828 dia. inch                  | Cooper           | CTX16-18405R        |
| 1     | PCB                               | Printed circuit board, HPA225                                       | Std              | Std                 |
| 2     | Q1, Q2                            | MOSFET, N-channel, 500 V, 7.1 A, 520 m $\Omega$ , TO-220V           | Infineon         | IPP50R520CP         |
| 2     | R1, R13                           | Resistor, chip, 1/10 W, 1%, 2.05 k $\Omega$ , 805                   | Std              | Std                 |
| 1     | R17                               | Resistor, chip, 1/10 W, 1%, 20.5 $\Omega$ , 805                     | Std              | Std                 |
| 4     | R2, R7, R11, R12                  | Resistor, chip, 1/10 W, 1%, 1.00 M $\Omega$ , 805                   | Std              | Std                 |
| 2     | R3, R14                           | Resistor, chip, 1/8 W, 1%, 33.2 $\Omega$ , 1206                     | Std              | Std                 |
| 2     | R4, R15                           | Resistor, chip, 1/10 W, 1%, 1.00 k $\Omega$ , 805                   | Std              | Std                 |
| 2     | R5, R18                           | Resistor, chip, 1/10 W, 1%, 5.11 $\Omega$ , 805                     | Std              | Std                 |
| 2     | R6, R16                           | Resistor, chip, 1/10 W, 1%, 2.49 k $\Omega$ , 805                   | Std              | Std                 |
| 4     | R8, R9, R10, R19                  | Resistor, chip, 1/10 W, 1%, 10.0 k $\Omega$ , 805                   | Std              | Std                 |
| 1     | RT1                               | Thermistor, NTC, 5 $\Omega$ , 6 A, 5 $\Omega$ , 0.180 X 0.550 inch  | Thermometrics    | CL-40               |

**Table 2. Mother Board (continued)**

| COUNT                      | REF DES                                     | DESCRIPTION   | MFR                  | PART NUMBER   |
|----------------------------|---|---|----------------------|---------------|
| 2                          | T1, T2                                      | Inductor, 140 $\mu$ H at 3.2 A PK, 0.360 X 0.520 inch | Cooper               | CTX16-18294-R |
| 1                          | U1  | Device, High Speed Low Side Power MOSFET Driver, SO8  | TI                   | UCC27324D     |
| 1                          | VAR1  | Varistor 275 V RMS, 0.472 x 0.213 inch                | Epcos                | S10K275E2     |
| <b>Additional Hardware</b> |   |   |                      |               |
| 1                          | X1 @ F1                                     | 4 A, fast acting fuse, 5 mm X 20 mm                   | Cooper/Bussman       | BK/S501-4-R   |
| 6                          | X1 @ HS1 and D3, HS2 and Q1, HS3 and Q2     | Nut #4-40 (steel)                                     | Std                  | Std           |
| 6                          | X1 @ HS1 and D3, HS2 and Q1, HS3 and Q2     | Pan head screw #4-40X3/8 (steel)                      | Std                  | Std           |
| 1                          | X1 D3 and HS1                               | Thermal grease  | Std                  | Std           |
| 6                          | X1 @ HS1 and D3, HS2 and Q1, HS3 and Q2     | Split lock washer #4(steel)                           | Std                  | Std           |
| 4                          | X1 @ HS1 and D3, HS2 and Q1, HS3 and Q2     | Nylon shoulder washer #4                              | Keystone Electronics | 3049          |
| 2                          | X1 @ HS2 and Q1, HS3 and Q2                 | Thermal pad silicon TO220                             | BERQUIST             | 3223-07FR-51  |
| 4                          | X1 @ HS2, HS3 None FET Side, Top and Bottom | External tooth washer #4                              | Std                  | Std           |

## 10.2 Daughter Board List of Materials

**Table 3. Daughter Board**

| COUNT | REF DES  | DESCRIPTION  | PART NUMBER     | MFR      |
|-------|----------|--|-----------------|----------|
| 1     | C1       | Capacitor, ceramic, 25 V, X7R, 10%, 1 $\mu$ F, 805               | Std             | Std      |
| 2     | C11, C12 | Capacitor, ceramic, 25 V, X7R, 10%, 100 nF, 805                  | Std             | Std      |
| 2     | C13, C14 | Capacitor, ceramic, 25 V, X7R, 10%, 330 pF, 805                  | Std             | Std      |
| 1     | C2       | Capacitor, ceramic, 25 V, X7R, 10%, 1.2 nF, 805                  | Std             | Std      |
| 1     | C3       | Capacitor, ceramic, 25 V, X7R, 10%, 150 pF, 805                  | Std             | Std      |
| 1     | C4       | Capacitor, ceramic, 25 V, X7R, 10%, 1.5 $\mu$ F, 805             | Std             | Std      |
| 1     | C5       | Capacitor, ceramic, 25 V, X7R, 10%, 150 nF, 805                  | Std             | Std      |
| 1     | C6       | Capacitor, ceramic, 25 V, X7R, 10%, 3.3 nF, 805                  | Std             | Std      |
| 2     | C7, C8   | Capacitor, ceramic, 25 V, X7R, 10%, 220 pF, 805                  | Std             | Std      |
| 2     | C9, C10  | Capacitor, ceramic, 25 V, X7R, 10%, 2.2 nF, 805                  | Std             | Std      |
| 1     | J1       | Header, right angle 10 pins, DF11-10DP-2DSxx, 0.394 x 0.472 inch | DF11-10DP-2DSxx | HRS      |
| 2     | JP1, JP2 | Header, 2 pin, 100 mil spacing, (36-pin strip), 0.100 inch x 2   | PTC36SAAN       | Sullins  |
| 2     | JP1, JP2 | Sockets jumper closed black                                      | 151-8010        | Kobiconn |
| 1     | PCB      | Daughter board PCB, HPA284                                       | Std             | Std      |
| 2     | R1, R2   | Resistor, chip, 1/10 W, 1%, 1.00 M $\Omega$ , 805                | Std             | Std      |
| 1     | R11      | Resistor, chip, 1/10 W, 1%, 3.65 k $\Omega$ , 805                | Std             | Std      |
| 1     | R12      | Resistor, chip, 1/10 W, 1%, 19.6 k $\Omega$ , 805                | Std             | Std      |
| 1     | R13      | Resistor, chip, 1/10 W, 1%, 38.30 k $\Omega$ , 805               | Std             | Std      |
| 1     | R14      | Resistor, chip, 1/10 W, 1%, 5.62 k $\Omega$ , 805                | Std             | Std      |
| 2     | R15, R16 | Resistor, chip, 1/10 W, 1%, 4.02 k $\Omega$ , 805                | Std             | Std      |
| 2     | R3, R4   | Resistor, chip, 1/10 W, 1%, 1.00 k $\Omega$ , 805                | Std             | Std      |
| 2     | R5, R10  | Resistor, chip, 1/10 W, 1%, 23.20 k $\Omega$ , 805               | Std             | Std      |
| 1     | R6       | Resistor, chip, 1/10 W, 1%, 46.40 k $\Omega$ , 805               | Std             | Std      |
| 1     | R7       | Resistor, chip, 1/10 W, 1%, 34.80 k $\Omega$ , 805               | Std             | Std      |
| 1     | R8       | Resistor, chip, 1/10 W, 1%, 37.40 k $\Omega$ , 805               | Std             | Std      |
| 1     | R9       | Resistor, chip, 1/10 W, 1%, 100.00 k $\Omega$ , 805              | Std             | Std      |
| 1     | U1       | Device, Two- Phases Interleaved CCM PFC Controller, TSSOP-20     | UCC28070PW      | TI       |

## EVALUATION BOARD/KIT IMPORTANT NOTICE

Texas Instruments (TI) provides the enclosed product(s) under the following conditions:

This evaluation board/kit is intended for use for **ENGINEERING DEVELOPMENT, DEMONSTRATION, OR EVALUATION PURPOSES ONLY** and is not considered by TI to be a finished end-product fit for general consumer use. Persons handling the product(s) must have electronics training and observe good engineering practice standards. As such, the goods being provided are not intended to be complete in terms of required design-, marketing-, and/or manufacturing-related protective considerations, including product safety and environmental measures typically found in end products that incorporate such semiconductor components or circuit boards. This evaluation board/kit does not fall within the scope of the European Union directives regarding electromagnetic compatibility, restricted substances (RoHS), recycling (WEEE), FCC, CE or UL, and therefore may not meet the technical requirements of these directives or other related directives.

Should this evaluation board/kit not meet the specifications indicated in the User's Guide, the board/kit may be returned within 30 days from the date of delivery for a full refund. **THE FOREGOING WARRANTY IS THE EXCLUSIVE WARRANTY MADE BY SELLER TO BUYER AND IS IN LIEU OF ALL OTHER WARRANTIES, EXPRESSED, IMPLIED, OR STATUTORY, INCLUDING ANY WARRANTY OF MERCHANTABILITY OR FITNESS FOR ANY PARTICULAR PURPOSE.**

The user assumes all responsibility and liability for proper and safe handling of the goods. Further, the user indemnifies TI from all claims arising from the handling or use of the goods. Due to the open construction of the product, it is the user's responsibility to take any and all appropriate precautions with regard to electrostatic discharge.

**EXCEPT TO THE EXTENT OF THE INDEMNITY SET FORTH ABOVE, NEITHER PARTY SHALL BE LIABLE TO THE OTHER FOR ANY INDIRECT, SPECIAL, INCIDENTAL, OR CONSEQUENTIAL DAMAGES.**

TI currently deals with a variety of customers for products, and therefore our arrangement with the user **is not exclusive**.

TI assumes **no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein.**

Please read the User's Guide and, specifically, the Warnings and Restrictions notice in the User's Guide prior to handling the product. This notice contains important safety information about temperatures and voltages. For additional information on TI's environmental and/or safety programs, please contact the TI application engineer or visit [www.ti.com/esh](http://www.ti.com/esh).

No license is granted under any patent right or other intellectual property right of TI covering or relating to any machine, process, or combination in which such TI products or services might be or are used.

### FCC Warning

This evaluation board/kit is intended for use for **ENGINEERING DEVELOPMENT, DEMONSTRATION, OR EVALUATION PURPOSES ONLY** and is not considered by TI to be a finished end-product fit for general consumer use. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to part 15 of FCC rules, which are designed to provide reasonable protection against radio frequency interference. Operation of this equipment in other environments may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

### EVM WARNINGS AND RESTRICTIONS

It is important to operate this EVM within the input voltage range of 85 to 265 VRMS and the output voltage range of 390 V  $\pm 15\%$ .

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than 50°C. The EVM is designed to operate properly with certain components above as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2008, Texas Instruments Incorporated



## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

### Products

|                             |  |
|-----------------------------|--|
| Amplifiers                  | <a href="http://amplifier.ti.com">amplifier.ti.com</a>             |
| Data Converters             | <a href="http://dataconverter.ti.com">dataconverter.ti.com</a>     |
| DLP® Products               | <a href="http://www.dlp.com">www.dlp.com</a>                       |
| DSP                         | <a href="http://dsp.ti.com">dsp.ti.com</a>                         |
| Clocks and Timers           | <a href="http://www.ti.com/clocks">www.ti.com/clocks</a>           |
| Interface                   | <a href="http://interface.ti.com">interface.ti.com</a>             |
| Logic                       | <a href="http://logic.ti.com">logic.ti.com</a>                     |
| Power Mgmt                  | <a href="http://power.ti.com">power.ti.com</a>                     |
| Microcontrollers            | <a href="http://microcontroller.ti.com">microcontroller.ti.com</a> |
| RFID                        | <a href="http://www.ti-rfid.com">www.ti-rfid.com</a>               |
| RF/IF and ZigBee® Solutions | <a href="http://www.ti.com/lprf">www.ti.com/lprf</a>               |

### Applications

|                    |  |
|--------------------|--|
| Audio              | <a href="http://www.ti.com/audio">www.ti.com/audio</a>                   |
| Automotive         | <a href="http://www.ti.com/automotive">www.ti.com/automotive</a>         |
| Broadband          | <a href="http://www.ti.com/broadband">www.ti.com/broadband</a>           |
| Digital Control    | <a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a> |
| Medical            | <a href="http://www.ti.com/medical">www.ti.com/medical</a>               |
| Military           | <a href="http://www.ti.com/military">www.ti.com/military</a>             |
| Optical Networking | <a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a> |
| Security           | <a href="http://www.ti.com/security">www.ti.com/security</a>             |
| Telephony          | <a href="http://www.ti.com/telephony">www.ti.com/telephony</a>           |
| Video & Imaging    | <a href="http://www.ti.com/video">www.ti.com/video</a>                   |
| Wireless           | <a href="http://www.ti.com/wireless">www.ti.com/wireless</a>             |

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2009, Texas Instruments Incorporated



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

**Телефон:** 8 (812) 309 58 32 (многоканальный)

**Факс:** 8 (812) 320-02-42

**Электронная почта:** [org@eplast1.ru](mailto:org@eplast1.ru)

**Адрес:** 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.